

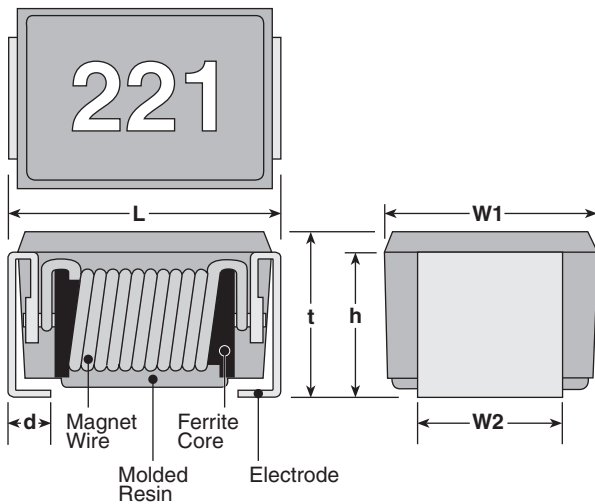


**features**

- UL94V0 molded epoxy case
- Suitable for reflow and wave soldering
- 1210 size - surface mount style
- High Q value achieved by wirewound structure
- Marking: Black body color with white marking
- Products with lead-free terminations meet EU RoHS requirements

Inductors

**dimensions and construction**



Type	Dimensions inches (mm)					
	L	W1	W2	t	h	d
KL32	.126±.008 (3.2±0.2)	.098±.008 (2.5±0.2)	.067±.004 (1.7±0.1)	.087±.008 (2.2±0.2)	.075±.004 (1.9±0.1)	.02 nominal (.5 nominal)

**Inductance Marking**

Value	Code
0.005μH - 0.082μH	005 - 082
0.10μH - 8.2μH	R10 - 8R2 R indicates decimal point.
10μH - 330μH	100 - 331 1st two figures are significant, the last figure indicates the number of zeros to follow.

**ordering information**

New Part #	KL	32	T	TE	101	J
Type		Size	Termination Material	Packaging	Nominal Inductance	Tolerance
		1210 size	T: Sn	TE: 7" embossed plastic TED: 10" embossed plastic (TE: 2,000 pieces/reel) (TED: 4,000 pieces/reel)	Reference inductance marking chart	J: ±5% K: ±10% M: ±20%

For further information on packaging, please refer to Appendix A.

applications and ratings

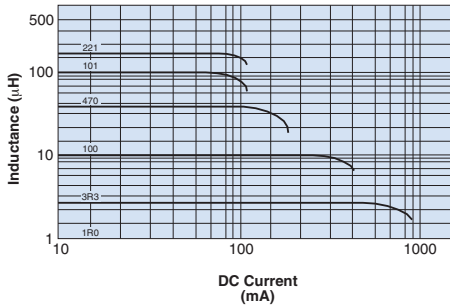
Part Designation	Inductance (µH)	Inductance Tolerance	Quality Factor Minimum	Self Resonant Frequency Minimum (MHz)	DC Resistance Maximum (Ω)	Allowable DC Current Maximum (mA)	Measured Frequency (MHz)	
KL32TTE005*	0.005	M: ±20%	11	2700	0.12	450	100	
KL32TTE010*	0.010	K: ±10% M: ±20%	15	2500	0.13			
KL32TTE012*	0.012		17	2300	0.14			
KL32TTE015*	0.015		19	2100	0.16			
KL32TTE018*	0.018		21	1900	0.18			
KL32TTE022*	0.022		23	1700	0.20			
KL32TTE027*	0.027		25	1500	0.22			
KL32TTE033*	0.033	J: ±5% K: ±10% M: ±20%	25	1400	0.24			
KL32TTE039*	0.039			1300	0.27			
KL32TTE047*	0.047		26	1200	0.30			
KL32TTE056*	0.056			1100	0.33			
KL32TTE068*	0.068		27	1000	0.36			
KL32TTE082*	0.082			900	0.40			
KL32TTER10*	0.10		J: ±5% K: ±10% M: ±20%	28	700			0.44
KL32TTER12*	0.12				500			0.22
KL32TTER15*	0.15			450	0.25			
KL32TTER18*	0.18			400	0.28			
KL32TTER22*	0.22			350	0.32			
KL32TTER27*	0.27			320	0.36			
KL32TTER33*	0.33	300		0.40				
KL32TTER39*	0.39	250		0.45				
KL32TTER47*	0.47	220		0.50				
KL32TTER56*	0.56	180		0.55				
KL32TTER68*	0.68	160		0.60				
KL32TTER82*	0.82	140		0.65				
KL32TTE1R0*	1.0	J: ±5% K: ±10% M: ±20%	30	120	0.70	400	7.96	
KL32TTE1R2*	1.2			100	0.75	390		
KL32TTE1R5*	1.5			85	0.85	370		
KL32TTE1R8*	1.8			80	0.90	350		
KL32TTE2R2*	2.2			75	1.0	320		
KL32TTE2R7*	2.7			70	1.1	290		
KL32TTE3R3*	3.3			60	1.2	260		
KL32TTE3R9*	3.9			55	1.3	250		
KL32TTE4R7*	4.7			50	1.5	220		
KL32TTE5R6*	5.6			47	1.6	200		
KL32TTE6R8*	6.8			43	1.8	180		
KL32TTE8R2*	8.2			40	2.0	170		
KL32TTE100*	10		36	2.1	150			
KL32TTE120*	12		33	2.5	140			
KL32TTE150*	15		30	2.8	130			
KL32TTE180*	18		27	3.3	120			
KL32TTE220*	22		25	3.7	110			
KL32TTE270*	27		20	5.0	80			
KL32TTE330*	33		17	5.6	70			
KL32TTE390*	39		16	6.4	65			
KL32TTE470*	47		15	7.0	60			
KL32TTE560*	56		13	8.0	55			
KL32TTE680*	68		12	9.0	50			
KL32TTE820*	82		11	10	45			
KL32TTE101*	100	10	10	40				
KL32TTE121*	120	20	10	11	70			
KL32TTE151*	150		8	15	65			
KL32TTE181*	180		7	17	60			
KL32TTE221*	220		7	21	50			
KL32TTE271*	270		6	28				
KL32TTE331*	330		5	34				

\* Add tolerance character (J, K, M)

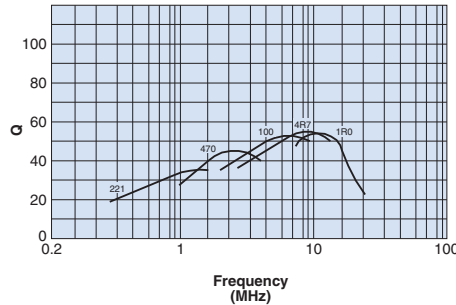
For complete environmental specifications, please refer to page 212.

## environmental applications

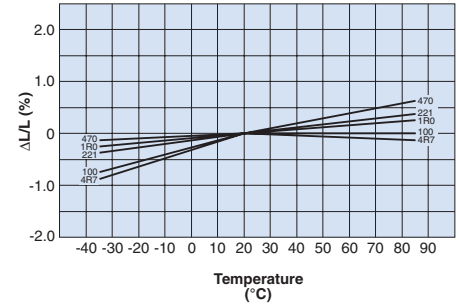
### DC Current Characteristics



### Q-Frequency Characteristics



### Temperature Characteristics



## Performance Characteristics

Parameter	Requirements Maximum Limit	Δ L/L Typical	Test Method
Resistance to Soldering Heat	Δ L/L: ±3%	Δ L/L: ±1.5%	260°C ± 5°C, 10s ± 1s
Heat Shock	Δ L/L: ±5%	Δ L/L: ±1.1%	-25°C (1 hour)/ +100°C (1 hour) 100 cycles
Low Temperature Operation	Δ L/L: ±5%, Δ Q/Q: ±20%	Δ L/L: ±0.9% Δ Q/Q: ±5.0%	-40°C ± 2°C, 1000h
High Temperature Exposure	Δ L/L: ±5%, Δ Q/Q: ±30%	Δ L/L: ±0.8% Δ Q/Q: ±5.0%	100°C ± 2°C, 1000h
Moisture Exposure	Δ L/L: ±5%, Δ Q/Q: ±30%	Δ L/L: ±1.3% Δ Q/Q: ±5.2%	40°C ± 2°C, 90%~95%RH, 1000h
Resistance to Solvent	No damage and marking shall be legible	—	Accordance with MIL-STD-202F Method 215